

**AMENDMENTS TO THE CLAIMS:**

***Claims 1-19 (cancelled)***

20. (Currently amended) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface ~~at a predetermined pressure~~  
so as to polish the workpiece; and  
at least two dressing units for dressing said polishing surface by being brought into contact  
with said polishing surface,  
wherein said at least two dressing units are to dress said polishing surface at different times,  
respectively, and are of a material that is different than that of the workpiece.

21. (Previously presented) The polishing apparatus according to claim 20, wherein  
said at least two dressing units include different dressers, respectively.

22. (Previously presented) The polishing apparatus according to claim 20, wherein  
at least one of said at least two dressing units includes a dresser having a diameter greater than  
a diameter of the workpiece to be polished, and  
at least one of said at least two dressing units includes a dresser having a diameter smaller than  
the diameter of the workpiece to be polished.

23. (Previously presented) The polishing apparatus according to claim 22, wherein  
said dresser having a diameter greater than a diameter of the workpiece to be polished  
comprises one of a ring-shaped dresser and a disk-shaped dresser, and  
said dresser having a diameter smaller than the diameter of the workpiece to be polished  
comprises one of a ring-shaped dresser and a disk-shaped dresser.

24. (Previously presented) The polishing apparatus according to claim 20, wherein said at least two dressing units are for dressing said polishing surface by re-generating said polishing surface.

***Claim 25 (cancelled)***

26. (Previously presented) The polishing apparatus according to claim 20, wherein said at least two dressing units are not co-axial with one another.

27. (Previously presented) The polishing apparatus according to claim 20, wherein said at least two dressing units are of different material relative to one another.

28. (Previously presented) The polishing apparatus according to claim 20, wherein there are at least twice as many dressing units as there are top rings.

29. (Previously presented) The polishing apparatus according to claim 20, wherein said at least two dressing units each have a contact surface for contacting said polishing surface during dressing of said polishing surface.

***Claims 30-31 (cancelled)***

32. (Currently amended) A polishing apparatus for polishing a workpiece, comprising:  
a table for providing a polishing surface;  
a first dresser having a contact surface comprising diamond particles for contacting said polishing surface during a first dressing operation;  
a second dresser having a contact surface comprising diamond particles for contacting said polishing surface during a second dressing operation; and  
an atomizer for spraying a fluid on said polishing surface to remove a polishing waste present on said polishing surface,

wherein said first dresser and said second dresser are to perform said first dressing operation and said second dressing operation at different times, respectively.

33. (Previously presented) A polishing apparatus for polishing a workpiece, comprising:  
a table for providing a polishing surface;  
a first dresser having a contact surface for contacting said polishing surface during a first dressing operation;  
a second dresser having a contact surface for contacting said polishing surface during a second dressing operation;  
a sensor for measuring a profile of said polishing surface; and  
a controller for controlling a dressing process of said first dresser,  
wherein said first dresser and said second dresser are to perform said first dressing operation and said second dressing operation at different times, respectively.

34. (Currently amended) A polishing apparatus comprising:  
a polishing table having a polishing surface;  
a top ring for pressing a workpiece against said polishing surface ~~at a predetermined pressure~~  
so as to polish the workpiece; ~~and~~  
at least two dressers for dressing said polishing surface, ~~wherein one of said at least two dressers is comprising a diamond dresser; and~~  
~~a controller for performing to perform~~ an initial surface conditioning of said polishing surface with said one of said at least two dressers at a time prior to polishing of any workpiece so as to thinly shave said polishing surface, and ~~another of said at least two dressers is for dressing said polishing surface~~ with another of said at least two dressers after the workpiece has been polished.

35. (Previously presented) The polishing apparatus according to claim 34, wherein  
said one of said at least two dressers is for performing the initial surface conditioning of said polishing surface only at the time prior to polishing of any workpiece, and

said another of said at least two dressers is for dressing said polishing surface only after a workpiece has been polished.

36. (Previously presented) The polishing apparatus according to claim 34, wherein said at least two dressers are different in size relative to one another.

37. (Currently amended) ~~The polishing apparatus according to claim 34,~~ A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and

at least two dressers for dressing said polishing surface,

wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished,

wherein at least one of said at least two dressers has a diameter greater than a diameter of the workpiece to be polished, and

wherein at least one of said at least two dressers has a diameter smaller than the diameter of the workpiece to be polished.

38. (Previously presented) The polishing apparatus according to claim 34, wherein one of said at least two dressers is to move across said polishing surface while dressing said polishing surface.

39. (Previously presented) The polishing apparatus according to claim 34, wherein at least one of said at least two dressers is to dress said polishing surface while the workpiece is not being polished.

40. (Previously presented) The polishing apparatus according to claim 34, wherein said at least two dressers comprise diamond dressers.

41. (Currently amended) The polishing apparatus according to claim 34, wherein ~~said one of said at least two dressers comprises a diamond dresser, and~~ said another of said at least two dressers comprises a brush dresser.

42. (Currently amended) ~~The polishing apparatus according to claim 34,~~ A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and

at least two dressers for dressing said polishing surface,

wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished, and

wherein one of said at least two dressers is to have at least one of its swing speed, rotational speed, and pressing load controlled based on a profile of a surface, to be polished, of the workpiece.

43. (Currently amended) ~~The polishing apparatus according to claim 34,~~ A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and

at least two dressers for dressing said polishing surface,

wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished, and

wherein one of said at least two dressers is to have at least one of its swing speed, rotational speed, and pressing load controlled based on a profile of said polishing surface.

44. (Currently amended) ~~The polishing apparatus according to claim 34, wherein said one of said at least two dressers is to dress said polishing surface after a plurality of workpieces has been polished~~ A polishing apparatus comprising:

a polishing table having a polishing surface;

a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece;

at least two dressers for dressing said polishing surface, with one of said at least two dressers comprising a diamond dresser; and

a controller for performing a dressing operation with said one of said at least two dressers after a plurality of workpieces has been polished, and for dressing said polishing surface with another of said at least two dressers each time a workpiece has been polished.

45. (Previously presented) The polishing apparatus according to claim 34, wherein said one of said at least two dressers is to dress said polishing surface when a polishing performance is not properly maintained.

46. (Previously presented) The polishing apparatus according to claim 45, wherein said one of said at least two dressers is to dress said polishing surface when the polishing performance is determined to not be properly maintained based on a profile of a surface, to be polished, of the workpiece not meeting a predetermined level requirement

47. (Previously presented) The polishing apparatus according to claim 34, further comprising:

an atomizer for spraying a fluid onto said polishing surface so as to remove a polishing waste present on said polishing surface.

48. (Previously presented) The polishing apparatus according to claim 47, wherein said atomizer is to spray a fluid composed of a mixture of gas and liquid.

49. (Previously presented) The polishing apparatus according to claim 47, wherein said atomizer is for spraying the fluid onto said polishing surface while the workpiece is not being polished.

50. (Previously presented) The polishing apparatus according to claim 47, wherein said atomizer is for spraying the fluid onto said polishing surface while said polishing surface is being dressed.